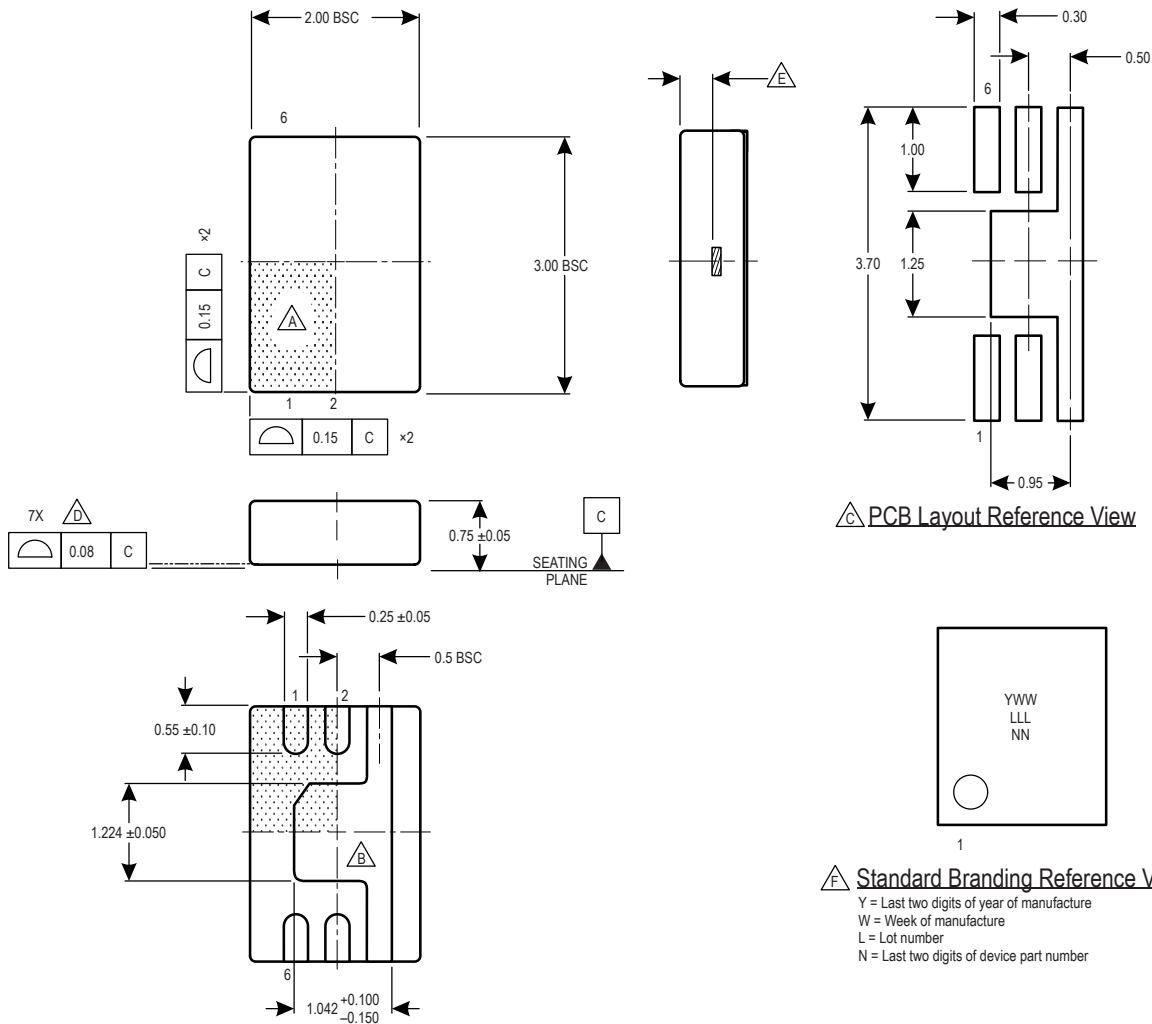


For Reference Only – Not for Tooling Use

(Reference Allegro DWG-0000373)
Dimensions in millimeters – NOT TO SCALE
Exact case and lead configuration at supplier discretion within limits shown



- A** Terminal #1 mark area
- B** Exposed thermal pad (reference only, terminal #1 identifier appearance at supplier discretion)
- C** Reference land pattern layout; all pads a minimum of 0.20 mm from all adjacent pads; adjust as necessary to meet application process requirements and PCB layout tolerances; when mounting on a multilayer PCB, thermal vias at the exposed thermal pad land can improve thermal dissipation (reference EIA/JEDEC Standard JESD51-5)

- D** Coplanarity includes exposed thermal pad and terminals
- E** Active Area Depth, 0.32 mm NOM
- F** Branding scale and appearance at supplier discretion

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